Title (en)

METHOD FOR IMPROVING THE MANUFACTURING SAFETY OF WELD JOINTS

Title (de)

VERFAHREN ZUR ERHÖHUNG DER FERTIGUNGSSICHERHEIT VON LÖTVERBINDUNGEN

Title (fr)

PROCEDE PERMETTANT D'AUGMENTER LA SECURITE DE FABRICATION DE LIAISONS SOUDEES

Publication

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Application

EP 00909014 A 20000208

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Abstract (en)

[origin: WO0054561A1] The invention relates to a method of improving the manufacturing safety of weld joints (7) between a ceramic support (1) and a printed-circuit board (10). Said method consists of the deposition of a first metallization layer (5) resistant to alloy breakdown on the ceramic support (1), followed by the imprinting of a second metallization layer (6), which enhances wetting behaviour, on the first metallization layer (5). In this way the thickness of the overall metallization layer (5, 6) can be increased in the area of the edges (8) of a weld joint (7). The resulting raised solder ring in turn permits the fully automatic optical control of the weld joint (7).

IPC 1-7

H05K 3/40; H05K 3/24; H05K 3/34; H01L 23/498

IPC 8 full level

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Citation (search report)

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